

Particle-in-cell simulation of vacuum arc ignition and development

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Mechanisms of Vacuum Arcs 2013,
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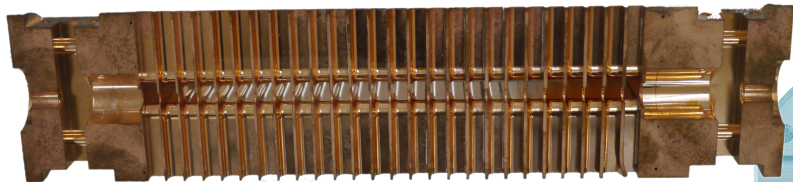
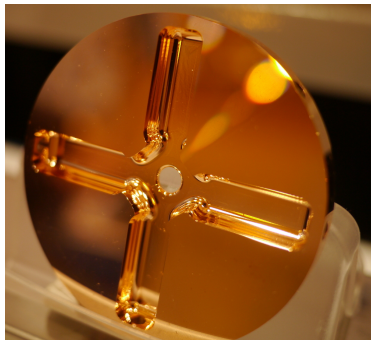
Outline

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 - Motivation
 - Physical system
- 2 Simulation code: ArcPic2D
- 3 Simulations
 - Arc evolution
 - Emission process
 - External circuit
- 4 System state
 - Surface
 - Plasma
- 5 Summary



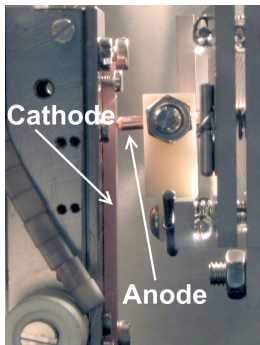
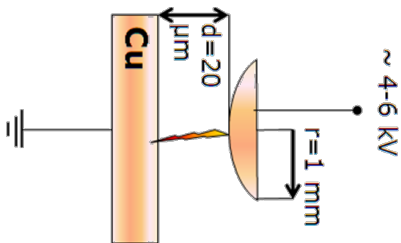
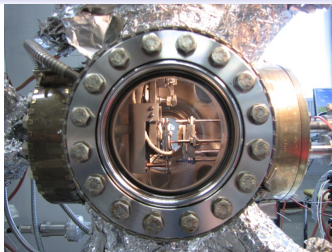
Motivation

- Want to build high-gradient ($E_{\text{acc}} \geq 100\text{MV/m}$) particle accelerators
 - Highest gradient achieved in normal-conducting structures
 - Gradient limited by arcs
 - Understand arc ignition!
- Design structures more resistant to arcing

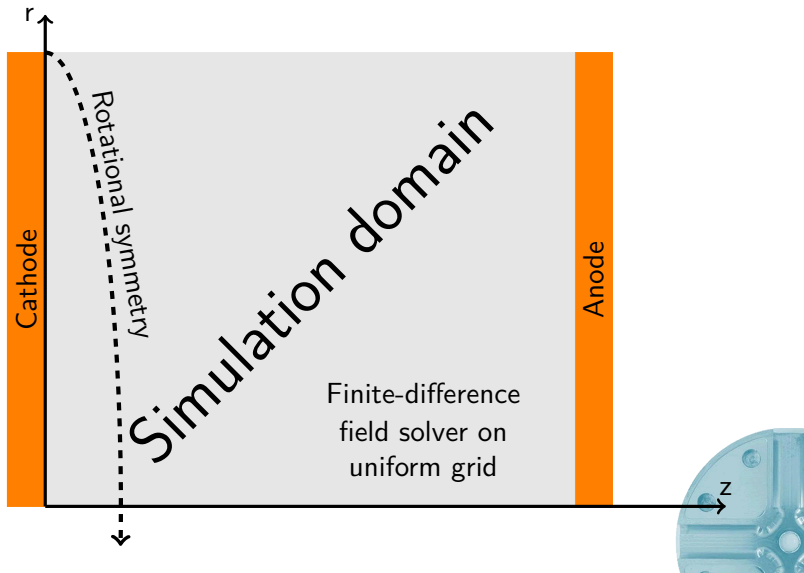


Experimental comparison: DC spark experiment

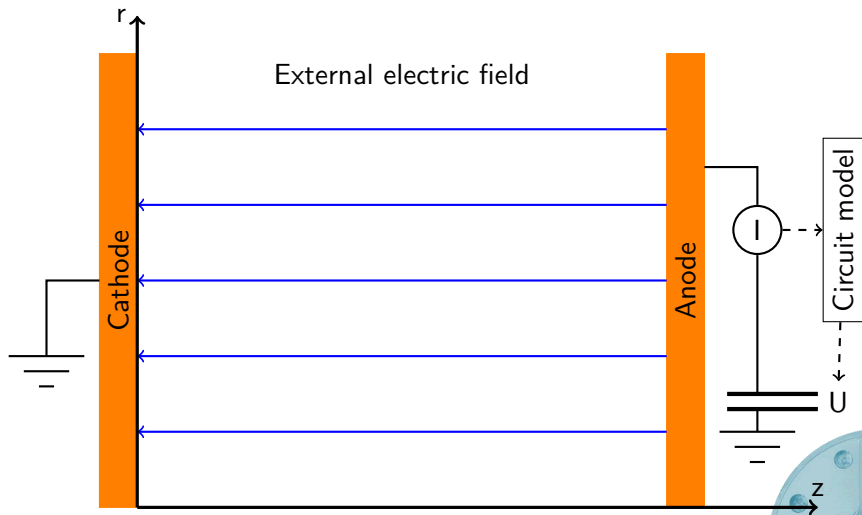
- High-voltage DC pulses on spark gap in ultra high vacuum
- Understand basic behavior of vacuum arc breakdowns
- Measure gap voltage & current through the breakdown



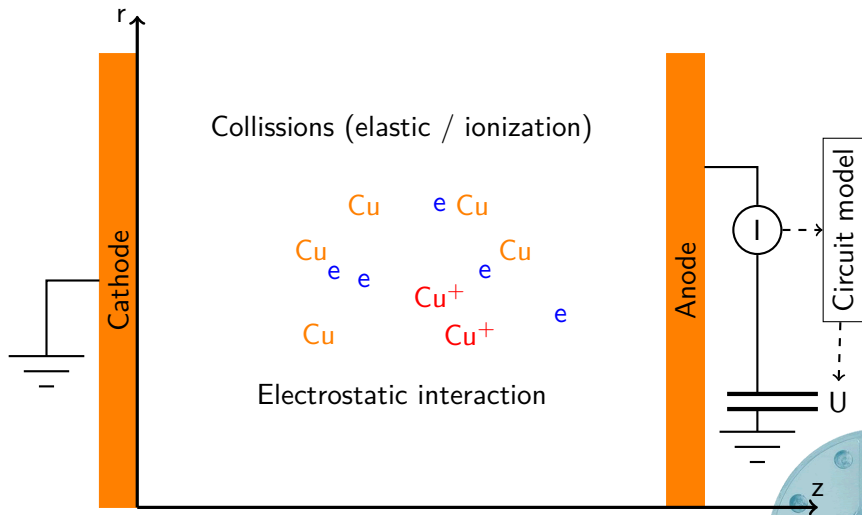
Physics model



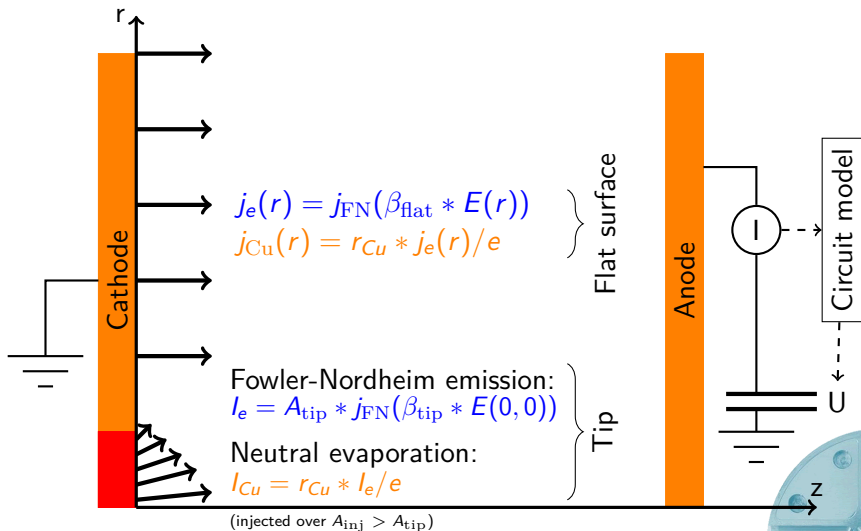
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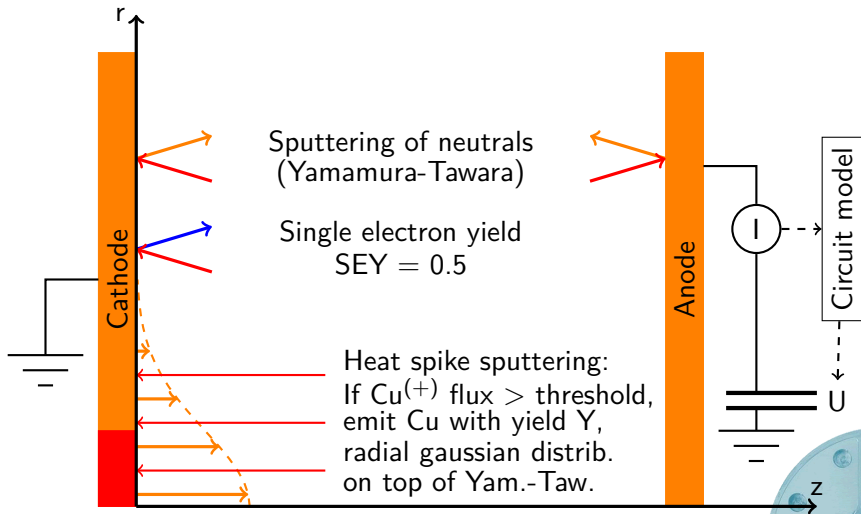
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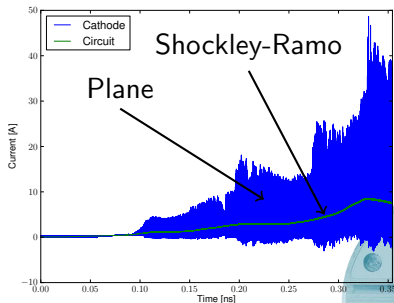


Physics model



Current calculation: Shockley-Ramo theorem

- Calculation of instantaneous currents on electrodes
 - Particles/time through plane incorrect & noisy
 - Noise is a problem for circuit models
- Use the Shockley-Ramo theorem to calculate currents
 - Charges in the gap induce charges on electrodes
 - Induced charge dependent on position
 - Moving charges \Rightarrow current
- Assumes electrostatic fields

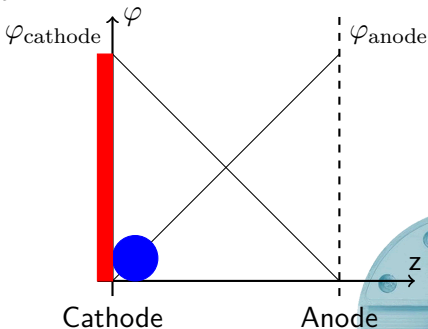


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Get φ for an electrode by solving $\nabla^2\varphi = 0$ with $\varphi = 1$ on electrode of interest, $\varphi = 0$ for all other electrodes.

$$Q_{\text{ind}} = -q\varphi(\vec{r})$$

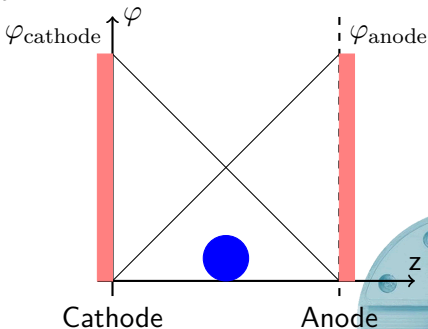


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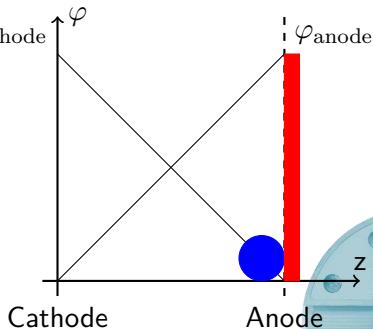


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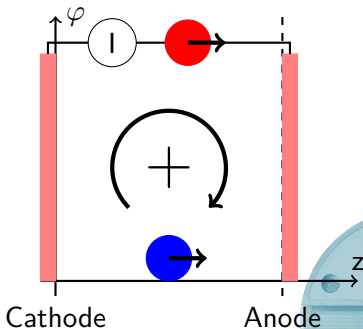


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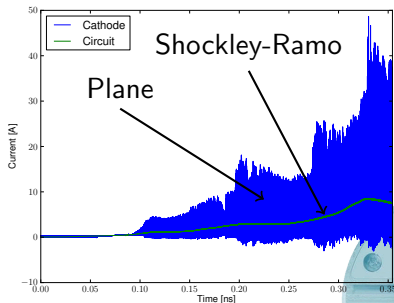


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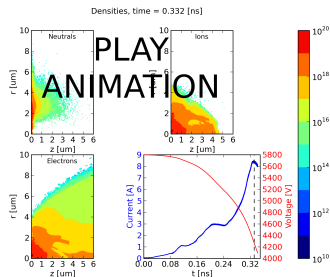
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Arc evolution

Main stages of vacuum arc ignition are visible:

- 1 Field emission and gas creation
- 2 Ionization
- 3 Bombardment and growth
 - Current growing together with transverse size
 - Capacitor discharged
 - Ions accelerated against field



Fast discharge:

- $U = 5800 \text{ V}$, $C = 0.5 \text{ pF}$
- $\beta_{\text{tip}} = 35$, $\beta_{\text{flat}} = 2$
- Heatspike $Y = 1$,
threshold = $10^{25} \text{ ions/cm}^2/\text{s}$
- Sim. domain $6 \times 24 \text{ } \mu\text{m}$
- $\Delta t = 0.9 \text{ fs}$, $\Delta z = 50 \text{ nm}$

Emission process

■ Parameters for emission:

■ Field emission:

$$\beta_{\text{tip}} = 35$$

$$\beta_{\text{flat}} = 1 / 2$$

■ Evaporation ratio

$$r_{\text{Cu}} = 0.015$$

■ Heatspike

$$\text{Yield} = 0 / 1 / 2$$

$$\text{threshold} = 10^{25} / \text{cm}^2 / \text{s}$$

■ Initial fields:

967 and 290 MV/m

■ Effects:

■ Time-to-breakdown

■ Speed of growth

■ Neutral/ion ratio



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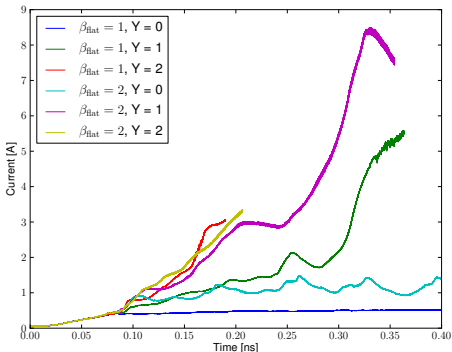
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- Increasing Y or β_{flat} \Rightarrow Faster growth
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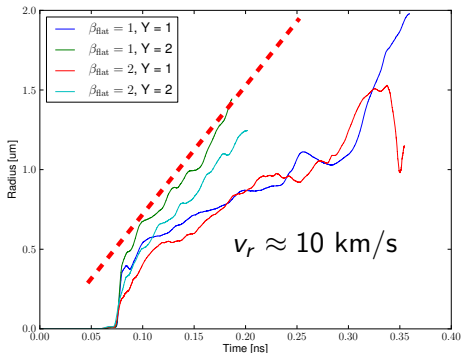
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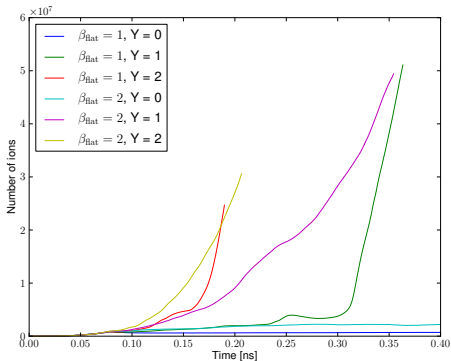
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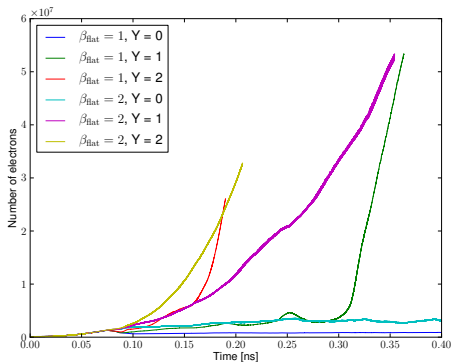
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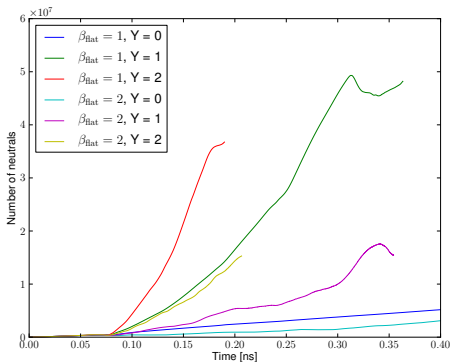
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- Less ionization with $\beta_{\text{flat}} = 1$

Emission process

Initial voltage = 1740 V:

■ Parameters for emission:

■ Field emission:

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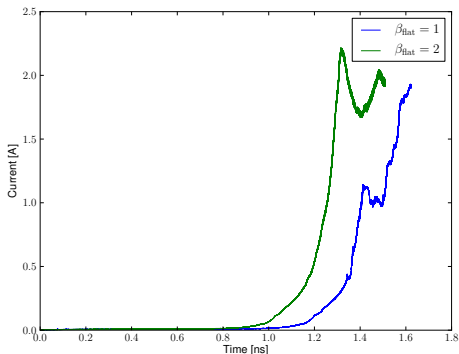
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- Lower voltage $\Rightarrow t_{\text{breakdown}}$ increased
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- Difference in $t_{\text{breakdown}}$ is random
(Start of runaway driven by tip)

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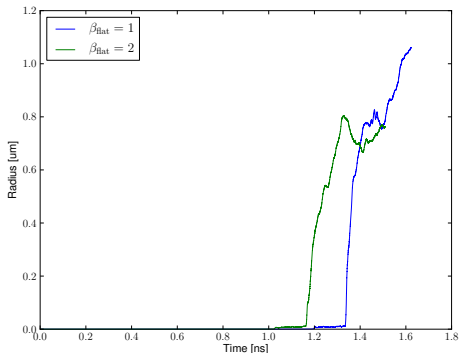
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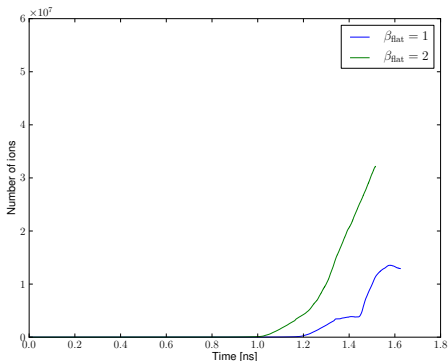
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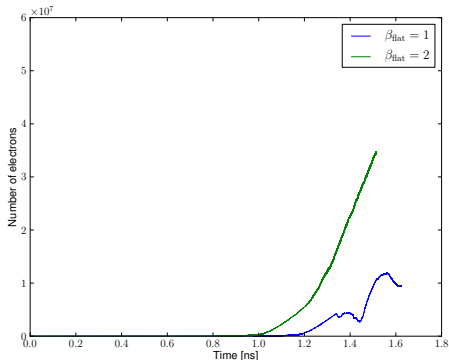
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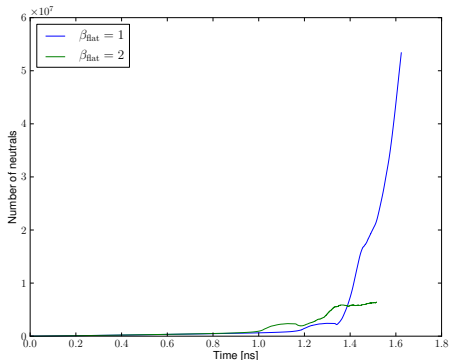
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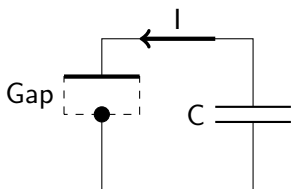
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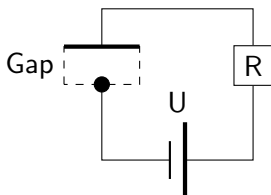
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External circuit

- Circuit types tested:
 - Capacitive – prev. slide
 - Resistive
- Varied parameters:
 - Resistance
 - Initial voltage
- All simulations ran with:
 - $\beta_{\text{tip}} = 35$, $\beta_{\text{flat}} = 2$
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$$V_{\text{gap}} = V_{t=0} - \frac{1}{C} \int_0^t I dt$$

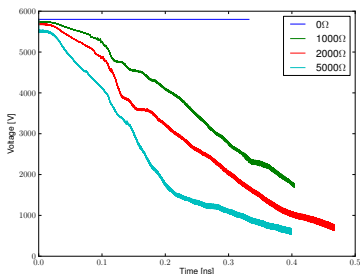
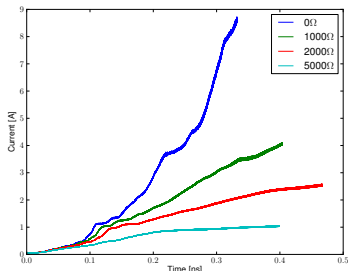


$$V_{\text{gap}} = U - RI$$

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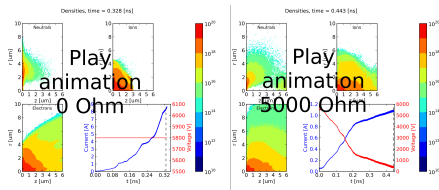
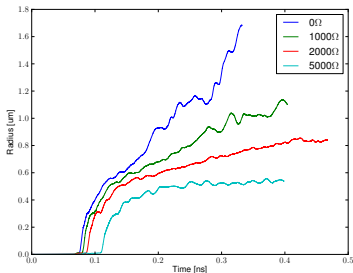
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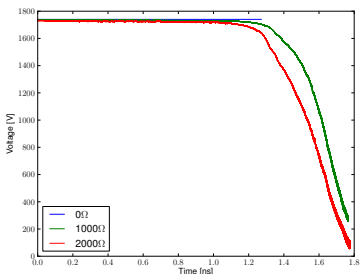
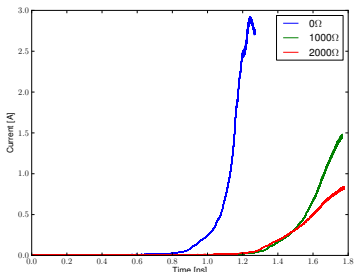
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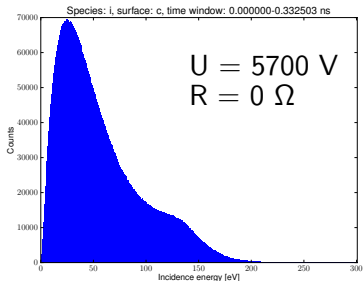
Results

- Smaller $U \Rightarrow$ longer $t_{\text{breakdown}}$
- Larger $R \Rightarrow$ slower growth
- Small $V_{\text{gap}} \Rightarrow$ plasma bridge



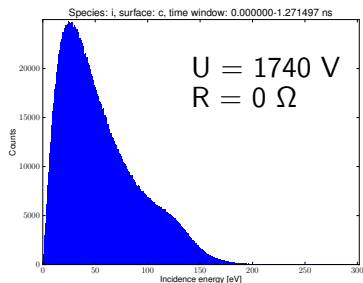
Ion bombardment of cathode

- Energy distribution mostly determined by sheath
 - Most probable value ≈ 30 eV
- Average yield from Yamamura-Tawara sputtering ≈ 0.1
 - Not enough to sustain arc
 - Heat-spike sputtering needed
- Bombardment flux density $\approx 10^{24} - 10^{25} / \text{cm}^2 / \text{s}$
- Slow “pulsing” in the bombardment
 - Associated with high gap voltage



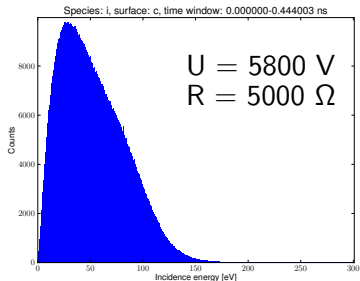
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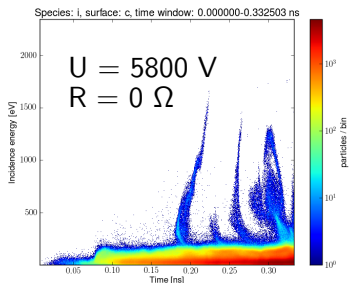
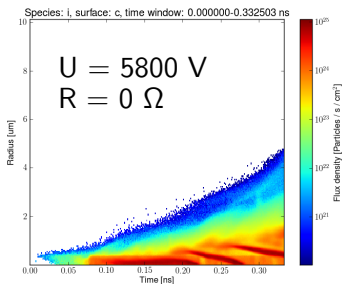
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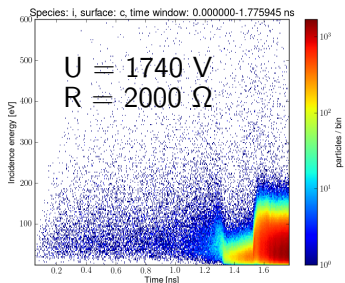
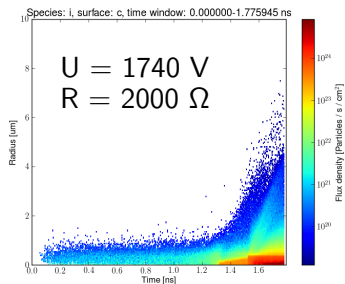
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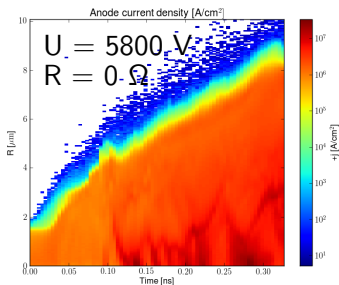
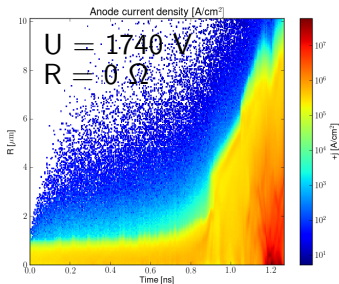
Ion bombardment of cathode

- Energy distribution mostly determined by sheath
 - Most probable value ≈ 30 eV
- Average yield from Yamamura-Tawara sputtering ≈ 0.1
 - Not enough to sustain arc
 - Heat-spike sputtering needed
- Bombardment flux density $\approx 10^{24} - 10^{25} / \text{cm}^2 / \text{s}$
- Slow “pulsing” in the bombardment
 - Associated with high gap voltage



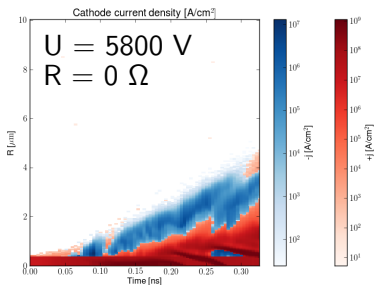
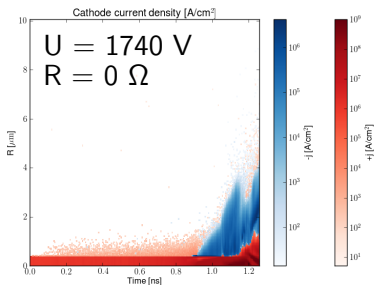
Surface current density

- Anode dominated by electron plume
 - Current densities reach $\approx 10^7 \text{ A/cm}^2$



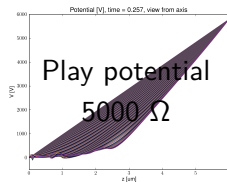
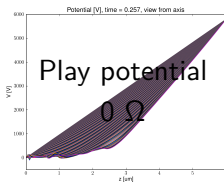
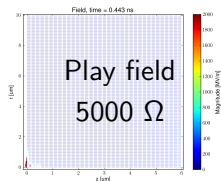
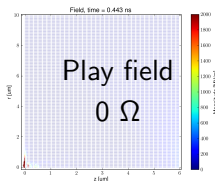
Surface current density

- Anode dominated by electron plume
 - Current densities reach $\approx 10^7 \text{ A/cm}^2$
- Cathode sees both electron emission, ion bombardment, and returning electrons
 - “Pulsing” can reverse current under sheath



Field distribution

- Sheath field $\approx 10\text{GV}/\text{m}$
- Field expelled from quasineutral plasma
 - Some oscillations still visible, fewer at smaller V_{gap}
- If V_{gap} remains high, high gradient between top of plasma and anode



All using resistive circuit,
 $U = 5800 \text{ V}$

Temperature

- If Maxwellian, velocity components are Gaussian

- $v = \mathcal{N}(\mu, \sigma)$

- $T_{[K]} = \frac{(\sigma_{[m/s]})^2 * m_{[kg]}}{k_{[J/K]}}$

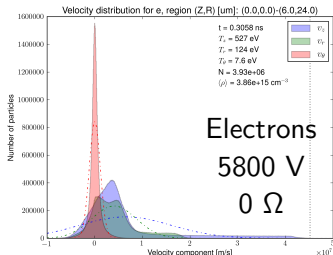
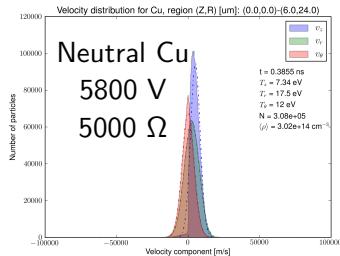
- or $T_{[eV]} = \frac{(\sigma_{[m/s]})^2 * m_{[kg]}}{e_{[J/eV]}}$

- To be expected if plasma dominated by collisions

- Not always the case
 - Especially at high gradients
 - Especially not for electrons

- Typical temperatures 5–20 eV (10^5 – 10^6 K)

- Higher at larger voltages
 - Where defined



Summary

- ArcPic2D: 2D3V PIC+MCC code
- Heat spike sputtering needed for plasma growth
- Higher voltage \Rightarrow
 - Shorter $t_{\text{breakdown}}$
 - Faster growth
 - Less anode splashing
 - More turbulent plasma
 - High gradient between plasma and anode
- Large circuit resistance \Rightarrow slower current growth
- Ion impact energy on cathode ≈ 30 eV
 - Defined by sheath
 - Independent of circuit and emission parameters
- Plasma densities $\approx 10^{20}$ ions/cm³
- “Temperatures” ≈ 5 -20 eV (ions & neutrals)
- Expansion rate ≈ 10 km/s

Thanks to: Lotta, Helga, Nick, Anders, Walter, Sergio

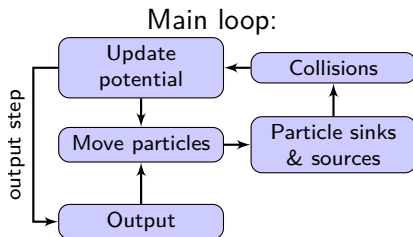


BACKUP SLIDES

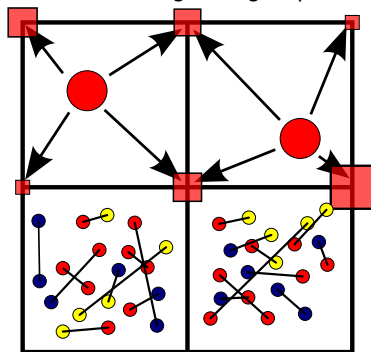


Particle in cell (PIC) + Monte Carlo Collisions (MCC)

- Volume divided into grid
 - Field solver
 - Proximity for collisions
- Macro-particles moves in continuous phase-space



Distribute charges to grid points



Collide random pairs of particles in each cell

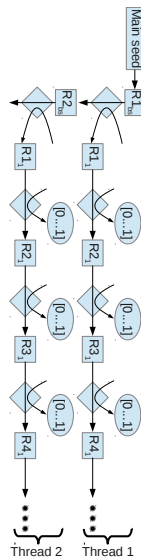
Monte-Carlo collisions

- Particles inside same cell are considered “close enough” to collide
- For each collision type, create random particle pairs
- Implemented collisions:
 - Coulomb scattering (e^-, e^-), (Cu^+, Cu^+), (Cu^+, e^-)
 - Elastic collisions (e^-, Cu), (Cu, Cu)
 - Charge exchange/momentum transfer (Cu^+, Cu)
 - Impact ionization $e^- + \text{Cu} \rightarrow 2 e^- + \text{Cu}^+$



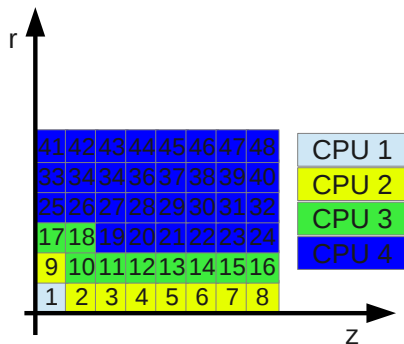
ArcPic2D parallelism

- OpenMP multithreading
 - Shared memory
 - Requiring few code changes
- Multi-stream RNG
- Parallel neutral-neutral collisions
- Load balancing
- Test case:
 - 1.8 M neutral particles
 - $5 \times 5 \mu\text{m}$ cylinder
 - $T=300 \text{ eV}$, $\rho = 10^{17} / \text{cm}^3$
- Quite good scaling
 - Almost linear
 - Slower than ideal due to serial sections



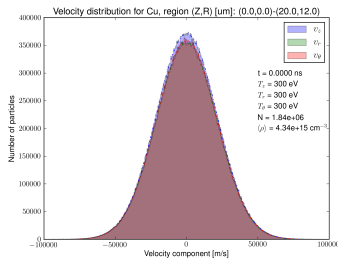
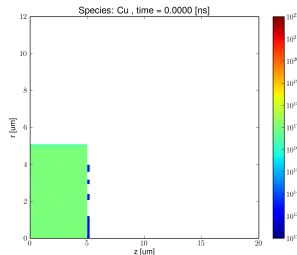
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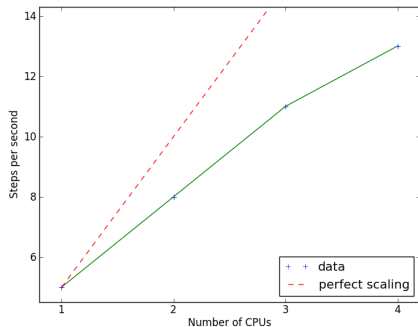
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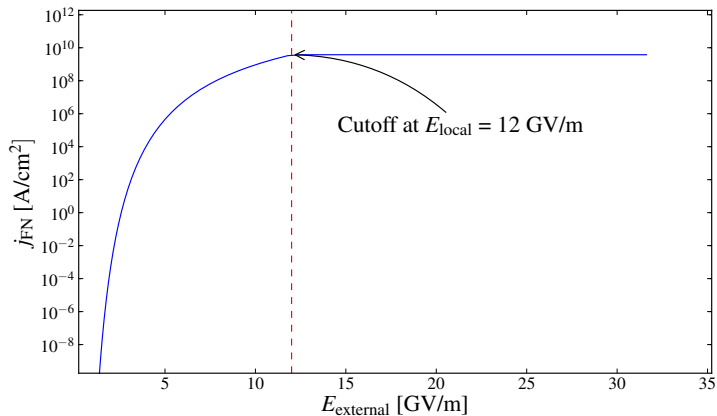


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Fowler-Nordheim emission



Yamamura-Tawara sputtering

